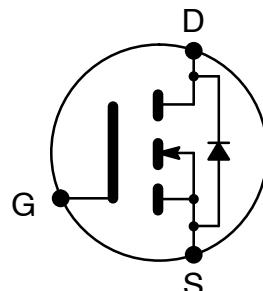


NTE2949
MOSFET
N-Channel, Enhancement Mode
High Speed Switch
TO-220 Full Pack Type Package

Features:

- Ultra Low Gate Charge
- Periodic Avalanche Rated
- Extreme dv/dt Rated
- High Peak Current Capability
- Improved Transconductance



Absolute Maximum Ratings:

Continuous Drain Current, I_D

$T_C = +25^\circ\text{C}$	20.7A
$T_C = +100^\circ\text{C}$	13.1A

Pulsed Drain Current (t_p limited by T_{Jmax}), I_{Dpuls}

62.1A

Single Pulse Avalanche Energy ($I_D = 10\text{A}$, $V_{DD} = 50\text{V}$), E_{AS}

690mJ

Repetitive Avalanche Energy (t_{AR} limited by T_{Jmax} , $I_D = 10\text{A}$, $V_{DD} = 50\text{V}$, Not 2), E_{AR}

1mJ

Repetitive Avalanche Current (t_{AR} limited by T_{Jmax}), I_{AR}

20A

Gate-Source Voltage, V_{GS}

Static	$\pm 20\text{V}$
AC ($f > 1\text{Hz}$)	$\pm 30\text{V}$

Total Power Dissipation ($T_C = +25^\circ\text{C}$), P_{tot}

34.5W

Reverse Diode dv/dt (Note 3), dv/dt

15V/ns

Drain-Source Voltage Slope ($V_{DS} = 480\text{V}$, $I_D = 20.7\text{A}$, $T_J = +125^\circ\text{C}$), dv/dt

50V/ns

Junction Temperature Range, T_J

-55° to +150°C

Storage Temperature Range, T_{stg}

-55° to +150°C

Lead Temperature (wavesoldering, .063" [1.6mm] from case, 10sec), T_{sold}

+260°C

Thermal Resistance, Junction-to-Case, R_{thJC}

3.6K/W

Thermal Resistance, Junction-to-Ambient, R_{thJA}

80K/W

Note 1. Limited only by maximum temperature.

Note 2. Repetitive avalanche causes additional power losses that can be calculated as $P_{AV} = E_{AR} + f$.

Note 3. $I_{SD} \leq I_D$, $di/dt \leq 400\text{A}/\mu\text{s}$, $V_{DClink} = 400\text{V}$, $V_{peak} < V_{(BR)DSS}$, $T_J < T_{Jmax}$, identical low-side and high-side switch.

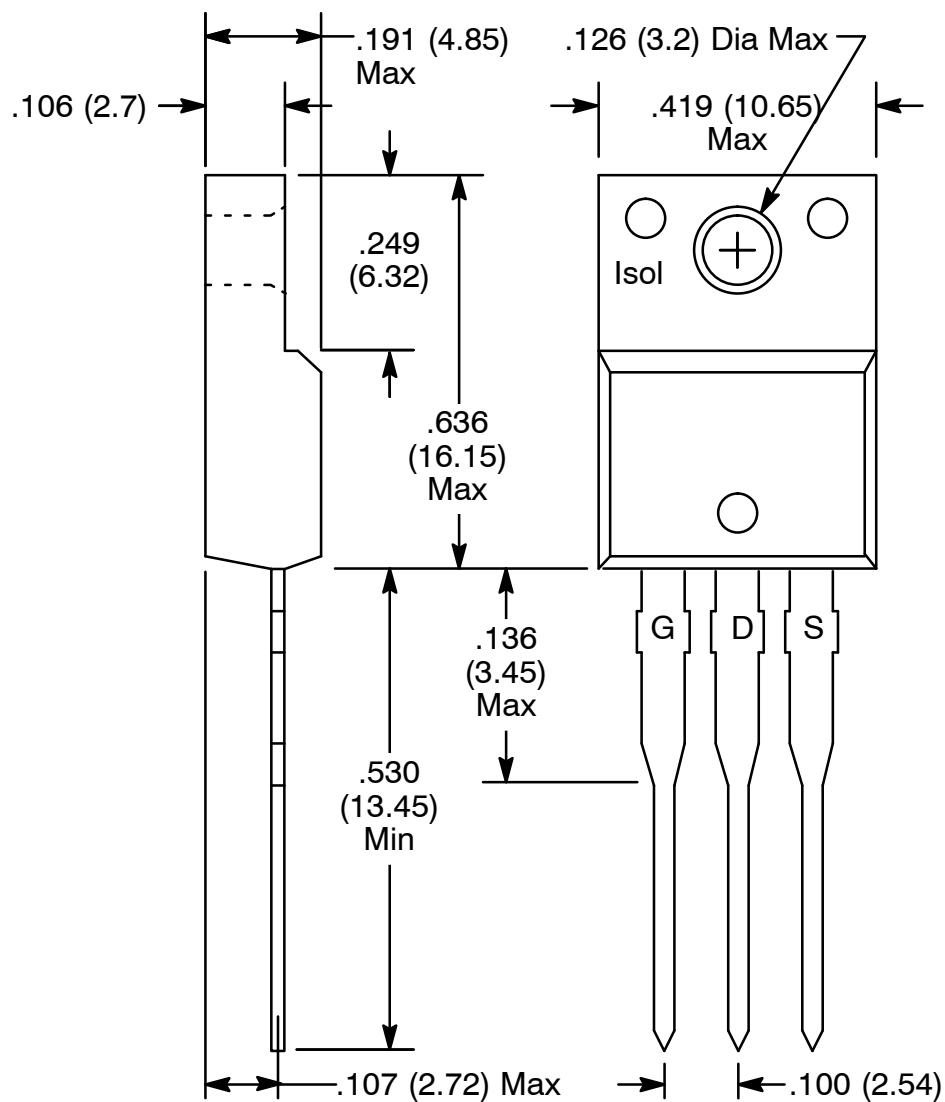


Electrical Characteristics: ($T_J = +25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Drain-Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	$V_{\text{GS}} = 0\text{V}, I_D = 0.25\text{mA}$	600	-	-	V
Gate-Source Avalanche Breakdown Voltage	$V_{(\text{BR})\text{DS}}$	$V_{\text{GS}} = 0\text{V}, I_D = 20\text{A}$	-	700	-	V
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$I_D = 1000\mu\text{A}, V_{\text{GS}} = V_{\text{DS}}$	2.1	3.0	3.9	V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{\text{DS}} = 600\text{V}, V_{\text{GS}} = 0, T_J = +25^\circ\text{C}$	-	0.1	1.0	μA
		$V_{\text{DS}} = 600\text{V}, V_{\text{GS}} = 0, T_J = +100^\circ\text{C}$	-	-	100	μA
Gate-Source Leakage Current	I_{GSS}	$V_{\text{GS}} = 30\text{V}, V_{\text{DS}} = 0\text{V}$	-	-	100	nA
Drain-Source ON-State Resistance	$R_{\text{DS}(\text{on})}$	$V_{\text{GS}} = 10\text{V}, I_D = 13.1\text{A}, T_J = +25^\circ\text{C}$	-	0.16	0.19	Ω
		$V_{\text{GS}} = 10\text{V}, I_D = 13.1\text{A}, T_J = +150^\circ\text{C}$	-	0.43	-	W
Gate Input Resistance	R_G	$f = 1\text{MHz}, \text{Open Drain}$	-	0.54	-	W
Transconductance	g_{fs}	$V_{\text{DS}} = 2 * I_D * R_{\text{DS}(\text{on})}\text{max}, I_D = 13.1\text{A}$	-	17.5	-	S
Input Capacitance	C_{iss}	$V_{\text{GS}} = 0\text{V}, V_{\text{DS}} = 25\text{V}, f = 1\text{MHz}$	-	2400	-	pF
Output Capacitance	C_{oss}		-	780	-	pF
Reverse Transfer Capacitance	C_{rss}		-	50	-	pF
Effective Output Capacitance, Energy Related	$C_{\text{o(er)}}$	$V_{\text{GS}} = 0\text{V}, V_{\text{DS}} = 0 \text{ to } 480\text{V}, \text{Note 4}$	-	83	-	pF
Effective Output Capacitance, Time Related	$C_{\text{o(tr)}}$	$V_{\text{GS}} = 0\text{V}, V_{\text{DS}} = 0 \text{ to } 480\text{V}, \text{Note 5}$	-	100	-	pF
Turn-On Delay Time	$t_{\text{d(on)}}$	$V_{\text{DD}} = 380\text{V}, V_{\text{GS}} = 0 \text{ to } 13\text{V}, I_D = 20.7\text{A}$	-	10	-	ns
Rise Time	t_r		-	5	-	ns
Turn-Off Delay Time	$t_{\text{d(off)}}$		-	67	100	ns
Fall Time	t_f		-	4.5	12	ns
Gate-Source Charge	Q_{gs}	$V_{\text{DD}} = 480\text{V}, I_D = 20.7\text{A}$	-	11	-	nC
Gate-Drain Charge	Q_{gd}		-	33	-	nC
Gate Charge Total	Q_g	$V_{\text{DD}} = 480\text{V}, I_D = 20.7\text{A}, V_{\text{GS}} = 0 \text{ to } 10\text{V}$	-	87	114	nC
Gate Plateau Voltage	$V_{(\text{plateau})}$	$V_{\text{DD}} = 480\text{V}, I_D = 20.7\text{A}$	-	5.5	-	V
Inverse Diode Continuous Forward Current	I_S	$T_C = 25^\circ\text{C}$	-	-	20.7	A
Inverse Diode Direct Current Pulsed	I_{SM}	$T_C = 25^\circ\text{C}$	-	-	62.1	A
Inverse Diode Forward Voltage	V_{SD}	$V_{\text{GS}} = 0\text{V}, I_F = I_S$	-	1.0	1.2	V
Reverse Recovery Time	t_{rr}	$V_R = 480\text{V}, I_F = I_S, \text{di}_F/\text{dt} = 100\text{A}/\mu\text{s}$	-	500	800	ns
Reverse Recovery Charge	Q_{rr}		-	11	-	μC
Peak Reverse Recovery Current	I_{rrm}		-	70	-	A
Peak Rate of Fall of Reverse Recovery Current	$\text{di}_{\text{rr}}/\text{dt}$	$T_J = +25^\circ\text{C}$	-	1400	-	$\text{A}/\mu\text{s}$

Note 4. $C_{\text{o(er)}}$ is a fixed capacitance that gives the same stored energy as C_{oss} while V_{DS} is rising from 0 to 80% V_{DSS} .

Note 5. $C_{\text{o(er)}}$ is a fixed capacitance that gives the same charging time as C_{oss} while V_{DS} is rising from 0 to 80% V_{DSS} .



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